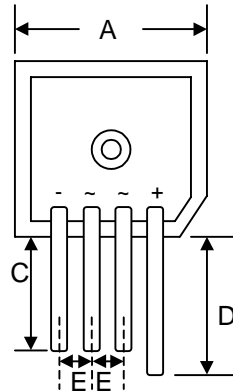


Features

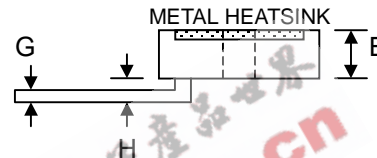
- Glass Passivated Die Construction
- Low Forward Voltage Drop
- High Current Capability
- High Reliability
- High Surge Current Capability
- Ideal for Printed Circuit Boards
- Designed for Saving Mounting Space

Mechanical Data

- Case: Epoxy Case with Heat Sink Internally Mounted in the Bridge Encapsulation
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Body
- Weight: 30 grams (approx.)
- Mounting Position: Any
- Marking: Type Number



KBPC-S		
Dim	Min	Max
A	28.40	28.70
B	10.97	11.23
C	13.90	—
D	19.10	—
E	5.10	—
G	1.20 Ø Typical	
H	3.05	3.60
All Dimensions in mm		



Maximum Ratings and Electrical Characteristics @T_A=25°C unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristics	Symbol	-00GS	-01GS	-02GS	-04GS	-06GS	-08GS	-10GS	Unit
Peak Repetitive Reverse Voltage	V _{RRM}								V
Working Peak Reverse Voltage	V _{RWM}	50	100	200	400	600	800	1000	
DC Blocking Voltage	V _R								
RMS Reverse Voltage	V _{R(RMS)}	35	70	140	280	420	560	700	V
Average Rectified Output Current @T _C = 55°C	I _O				15				A
Non-Repetitive Peak Forward Surge Current, 8.3ms Single Half-sine-wave Superimposed on Rated Load (JEDEC Method)	I _{FSM}				300				A
Forward Voltage Drop (per element)	V _{FM}				1.1				V
Peak Reverse Current at Rated DC Blocking Voltage (per element)	I _R				5.0				μA
					500				
I ² t Rating for Fusing (t < 8.3ms) (Note 1)	I ² t				374				A ² s
					374				
					664				
Typical Thermal Resistance (per element) (Note 2)	R _{θJC}				2.0				K/W
RMS Isolation Voltage from Case to Lead	V _{ISO}				2500				V
Operating and Storage Temperature Range	T _J , T _{STG}				-65 to +150			°C	

Note: 1. Non-repetitive for t > 1ms and < 8.3ms.

2. Thermal resistance junction to case per element mounted on 220 x 220 x 50mm thick AL plate.

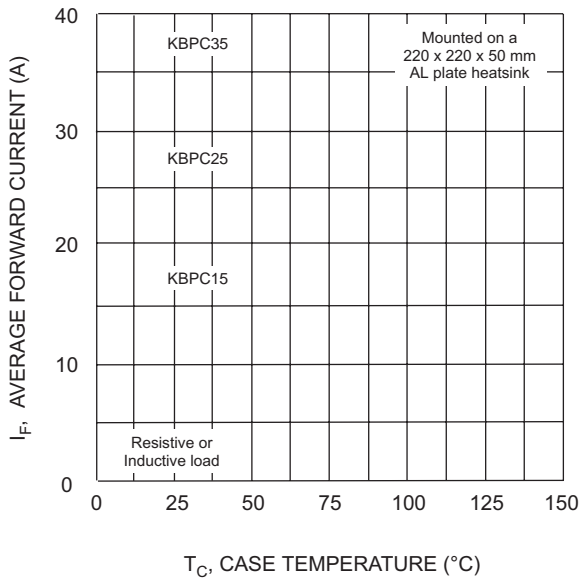


Fig. 1 Forward Current Derating Curve

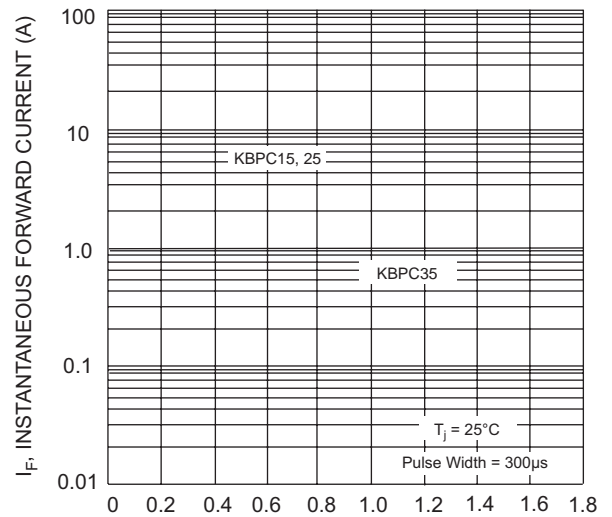


Fig. 2 Typical Forward Characteristics (per element)

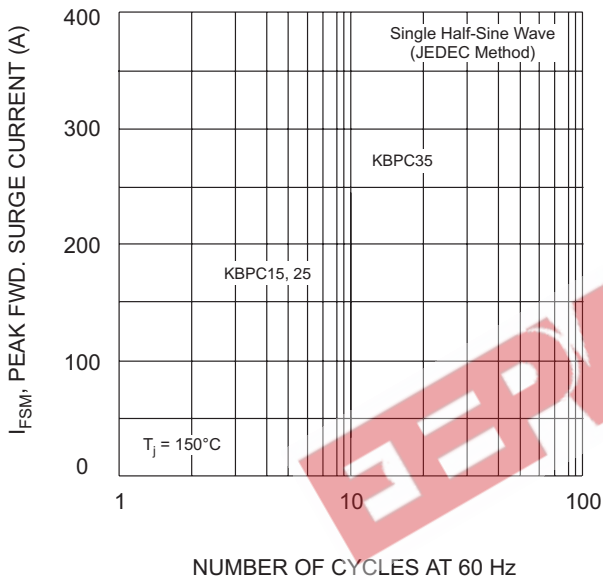


Fig. 3 Max Non-Repetitive Surge Current

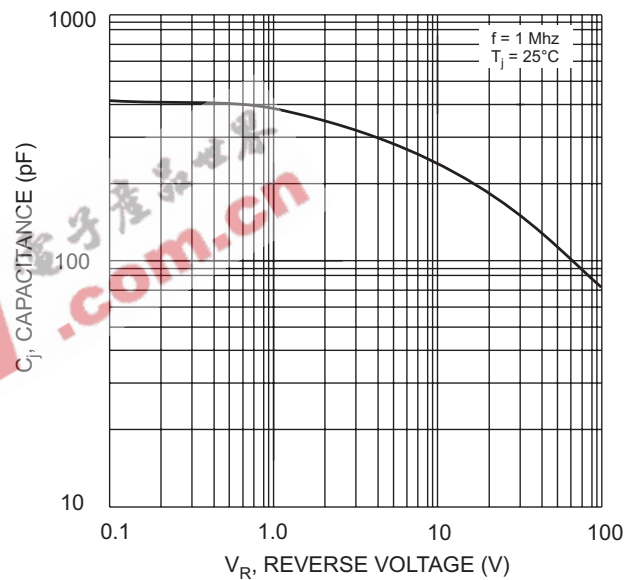


Fig. 4 Typical Junction Capacitance (per element)

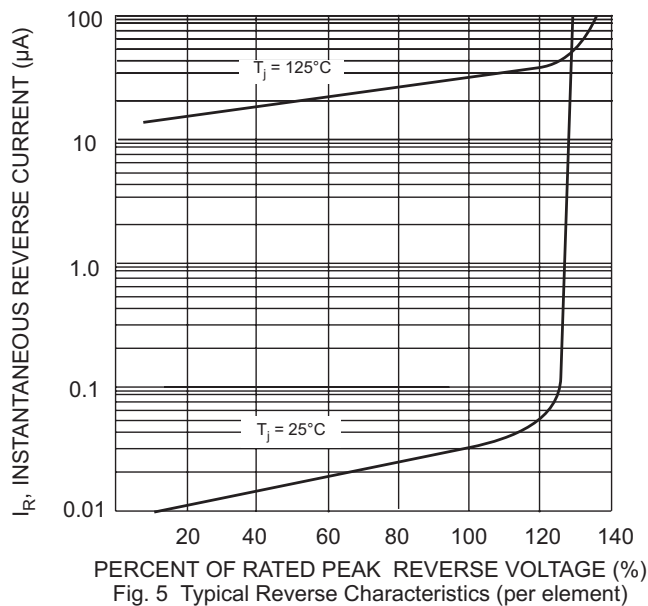


Fig. 5 Typical Reverse Characteristics (per element)

ORDERING INFORMATION

Product No.	Package Type	Shipping Quantity
KBPCxx00GS	SIL Bridge	72 Units/Box
KBPCxx01GS	SIL Bridge	72 Units/Box
KBPCxx02GS	SIL Bridge	72 Units/Box
KBPCxx04GS	SIL Bridge	72 Units/Box
KBPCxx06GS	SIL Bridge	72 Units/Box
KBPCxx08GS	SIL Bridge	72 Units/Box
KBPCxx10GS	SIL Bridge	72 Units/Box

Shipping quantity given is for minimum packing quantity only. For minimum order quantity, please consult the Sales Department.

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Won-Top Electronics Co., Ltd.

No. 44 Yu Kang North 3rd Road, Chine Chen Dist., Kaohsiung, Taiwan

Phone: 886-7-822-5408 or 886-7-822-5410

Fax: 886-7-822-5417

Email: sales@wontop.com

Internet: <http://www.wontop.com>

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